

International Application No.: PCT/JP2005/019286  
U.S. Patent Application No.: Unknown  
August 11, 2006  
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**AMENDMENTS TO THE SPECIFICATION:**

A substitute specification and a marked-up copy of the English translation of the originally filed PCT application are attached hereto.

Please replace the Title of the Invention originally filed with the above-identified patent application with the following new Title:

MULTILAYER SUBSTRATE WITH BUILT-IN CHIP-TYPE ELECTRONIC  
COMPONENT AND METHOD FOR MANUFACTURING THE SAME